HIGH SPEED 36K (4K X 9) IDT70914S SYNCHRONOUS DUAL-PORT RAM

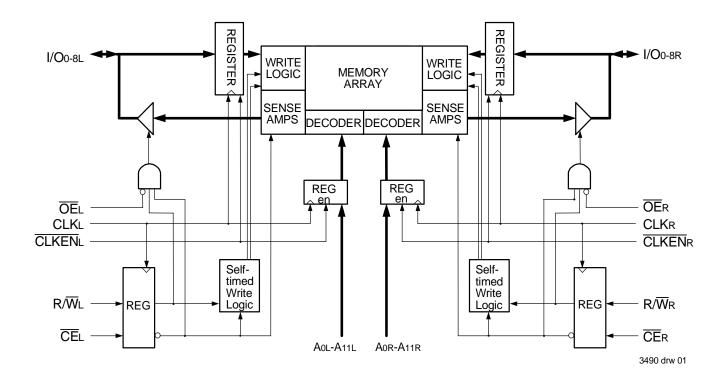
LEAD FINISH (SnPb) ARE IN EOL PROCESS - LAST TIME BUY EXPIRES JUNE 15, 2018

Features

- High-speed clock-to-data output times
 Commercial: 12/15/20ns (max.)
- Low-power operation
 - IDT70914S
 Active: 850 mW (typ.)
 Standby: 50 mW (typ.)
- Architecture based on Dual-Port RAM cells
- Allows full simultaneous access from both ports
- Synchronous operation
 - *Ans setup to clock, 1ns hold on all control, data, and address inputs*

- Data input, address, and control registers
- Fast 12ns clock to data out
- Self-timed write allows fast cycle times
- 16ns cycle times, 60MHz operation
- Clock Enable feature
- TTL-compatible, single 5V (± 10%) power supply
- Guaranteed data output hold times
- Available in 68-pin PLCC, and 80-pin TQFP
- Industrial temperature range (-40°C to +85°C) is available for selected speeds
- Green parts available, see ordering information

Functional Block Diagram



Description

The IDT70914 is a high-speed 4K x 9 bit synchronous Dual-Port RAM. The memory array is based on Dual-Port memory cells to allow simultaneous access from both ports. Registers on control, data, and address inputs provide low set-up and hold times. The timing latitude provided by this approach allow systems to be designed with very short cycle times. With an input data register, this device has been optimized for applications having unidirectional data flow or bidirectional data flow in bursts.

The IDT70914 utilizes a 9-bit wide data path to allow for parity at the

user's option. This feature is especially useful in data communication applications where it is necessary to use a parity bit for transmission/ reception error checking.

Fabricated using CMOS high-performance technology, these Dual-Ports typically operate on only 850mW of power at maximum high-speed clock-to-data output times as fast as 12ns. An automatic power down feature, controlled by \overline{CE} , permits the on-chip circuitry of each port to enter a very low standby power mode.

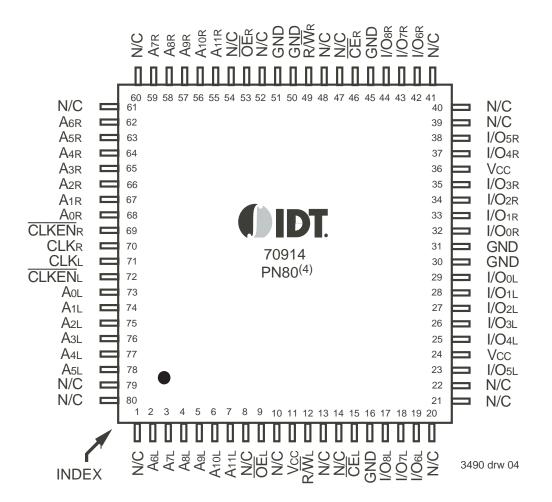
The IDT70914 is packaged in a 68-pin PLCC, and an 80-pin TQFP.

26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 N/C 9 A5L 27 8 Γ I/O5L 28 A4L Vcc 29 7 Азl I/O4L 30 6 A2L I/O3L] 31 5 A1L I/O2L AOL] 32 4 33 **CLKEN**L I/O1L 3 Γ **CLKL** I/OOL 34 2 [70914 GND 35 **CLK**R 1 J68⁽⁴⁾ GND] 36 68 [**CLKEN**R AOR I/OOR 37 67 I/O1R A1R 38 66 [I/O_{2R} 39 65 [A2R I/O3R] 40 64 [A3R Vcc] 41 63 [A4R] 42 62 [I/O4r A5r] 43 61 [I/O5R A6R 44 45 46 47 48 49 50 51 52 53 54 55 56 57 58 59 60 //Orr //Orr //Orr //Orr //Orr //Orr ///Orr //Orr ///Orr ///Orr //Orr ///Orr ///Orr //Orr //O/Orr //Orr //Orr //Orr ///Orr ///Orr////Orr///Orr////Orr////Orr/ 3490 drw 03

PinConfigurations^(1,2,3)

- 1. All Vcc pins must be connected to power supply.
- 2. All ground pins must be connected to ground supply.
- 3. J68-1 package body is approximately .95 in x .95 in x .17 in.
- 4. This package code is used to reference the package diagram.

Pin Configuration^(1,2,3) (con't.)



- 1. All Vcc pins must be connected to power supply.
- 2. All ground pins must be connected to ground supply.
- 3. PN80-1 package body is approximately 14mm x 14mm x 1.4mm.
- 4. This package code is used to reference the package diagram.

Absolute Maximum Ratings⁽¹⁾

Symbol	ymbol Rating Com'l Only			
Vterm ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	V	
VTERM ⁽²⁾	Terminal Voltage	-0.5 to Vcc	V	
Tbias	Temperature Under Bias	-55 to +125	٥C	
Tstg	Storage Temperature	-65 to +150	٥C	
Ιουτ	DC Output Current	50	mA	

NOTES:

3490 tbl 01

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed Vcc + 10% for more than 25% of the cycle time or 10ns maximum, and is limited to \leq 20mA for the period of VTERM \geq Vcc + 10%.

Capacitance

 $(TA = +25^{\circ}C, f = 1.0MHz)$ TQFP Only

	Symbol	Parameter	Conditions	Max.	Unit
	CiN	Input Capacitance	VIN = 3dV	8	pF
	Соит	Output Capacitance	Vout = 3dV	9	pF
					3490 tbl 04

NOTES:

 These parameters are determined by device characterization, but are not production tested.

3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.

Maximum Operating Temperature and Supply Voltage^(1,2)

Grade	Ambient Temperature	GND	Vcc
Commercial	0°C to +70°C	0V	5.0V <u>+</u> 10%
			3490 tbl 02

NOTES:

1. This is the parameter TA. This is the "instant on" casae temperature

2. Industrial temperature: for specific speeds, packages and powers contact your

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit	
Vcc	Supply Voltage	4.5	5.0	5.5	V	
GND	Ground	0	0	0	V	
V⊮	Input High Voltage	2.2	_	6.0 ⁽²⁾	V	
Vil	Input Low Voltage	-0.5 ⁽¹⁾		0.8	V	
3490 tbl 03						

NOTES:

1. VIL \geq -1.5V for pulse width less than 10ns.

2. VTERM must not exceed Vcc + 10%.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (Vcc = 5.0V ± 10%)

			70914S		
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
lu	Input Leakage Current ⁽¹⁾	Vcc = 5.5V, VIN = 0V to Vcc	_	10	μA
Ilo	Output Leakage Current	\overline{CE} = VH, VOUT = 0V to VCC	_	10	μA
Vol	Output Low Voltage	Iol = +4mA	-	0.4	V
Vон	Output High Voltage	Ioh = -4mA	2.4	-	V

NOTE:

1. At Vcc < 2.0V, input leakages are undefined

3490 tbl 05

3490 tbl 06b

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽⁴⁾ ($Vcc = 5V \pm 10\%$)

				70914S12 Com'l Only		7091 Com'		
Symbol	Parameter	Test Condition	Version	Typ. ⁽²⁾	Max.	Тур. ⁽²⁾	Max.	Unit
lcc	Dynamic Operating Current (Both Ports Active)	$\label{eq:cell} \begin{array}{l} \overline{CE}L \text{ and } \overline{CE}R = V_{IL},\\ Outputs \text{ Disabled} \\ f = f_{MAX}^{(1)} \end{array}$	COM'L	190	310	180	300	mA
ISB1	Standby Current (Both Ports - TTL Level Inputs)	\overline{CE}_{L} and $\overline{CE}_{R} = V_{IH}$ f = fmax ⁽¹⁾	COM'L	95	150	90	140	mA
ISB2	Standby Current (One Port - TTL Level Inputs)	$ \frac{\overline{CE}^* A^* = VIL \text{ and } }{\overline{CE}^* B^* = VIH^{(3)} } $	COM'L	170	220	160	210	mA
ISB3	Full Standby Current (Both Ports - All CMOS Level Inputs)	$\begin{array}{l} \hline Both \mbox{ Ports } \overline{\mbox{CE}}_R \mbox{ and } \\ \hline \overline{\mbox{CE}}_L \geq Vcc \ \ - \ 0.2V \\ \hline V_IN \geq Vcc \ \ - \ 0.2V \mbox{ or } \\ \hline V_IN \leq 0.2V, \ f = \ 0^{(2)} \end{array}$	COM'L	10	15	10	15	mA
ISB4	Full Standby Current (One Port - All CMOS Level Inputs)	$\begin{array}{l} \overline{\underline{CE}}^{*} A^{*} \leq 0.2V \text{ and} \\ \overline{CE}^{*} B^{*} \geq Vcc \ - \ 0.2V^{(3)} \\ \forall \mathbb{N} \geq Vcc \ - \ 0.2V \text{ or} \\ \forall \mathbb{N} \leq 0.2V, \text{ Active Port} \\ Outputs \ Disabled \\ f = f_{MAX}^{(1)} \end{array}$	COM'L	165	210	155	200	mA

						3490 tbl 06a
				70914S20 Com'l Only		
Symbol	Parameter	Test Condition	Version	Тур. ⁽²⁾	Max.	Unit
lcc	Dynamic Operating Current (Both Ports Active)	$\label{eq:cell} \overline{CE}L \text{ and } \overline{CE}R = VIL, \\ Outputs Disabled \\ f = fMAx^{(1)}$	COM'L	170	290	mA
ISB1	Standby Current (Both Ports - TTL Level Inputs)	\overline{CE}_{L} and $\overline{CE}_{R} = V_{IH}$ f = fMax ⁽¹⁾	COM'L	85	130	mA
ISB2	Standby Current (One Port - TTL Level Inputs)	$\label{eq:constraint} \begin{array}{ c c } \overline{CE}^{*} A^{*} &= V \text{IL and} \\ \overline{CE}^{*} B^{*} &= V \text{IH}^{(3)} \\ \text{Active Port Outputs} \\ \text{Disabled, } f=f \text{MAX}^{(1)} \end{array}$	COM'L	150	200	mA
ISB3	Full Standby Current (Both Ports - All CMOS Level Inputs)	$\begin{array}{l} \underline{Both} \ Ports \ \overline{CE}_{R} \ and \\ \overline{CE}_{L} \geq Vcc \ - \ 0.2V \\ V N \geq Vcc \ - \ 0.2V \ or \\ V N \leq \ 0.2V, \ f = \ 0^{(2)} \end{array}$	COM'L	10	15	mA
ISB4	Full Standby Current (One Port - All CMOS Level Inputs)	$\begin{array}{l} \overline{CE}^{"A"} \leq 0.2V \text{ and} \\ \overline{CE}^{"B"} \geq V_{CC} - 0.2V^{(3)} \\ V_{IN} \geq V_{CC} - 0.2V \text{ or} \\ V_{IN} \leq 0.2V, \text{ Active Port} \\ Outputs Disabled \\ f = fMax^{(1)} \end{array}$	COM'L	145	190	mA

NOTES:

1. At fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcvc, using "AC TEST CONDITIONS" at input levels of GND to 3V.

2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.

3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".

4. Vcc = 5V, Ta = 25°C for Typ, and are not production tested. Icc pc = 150mA (Typ)

5. Industrial temperature: for specific speeds, packages and powers contact your sales office.

Commercial Temperature Range

AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1,2 and 3

3490 tbl 07

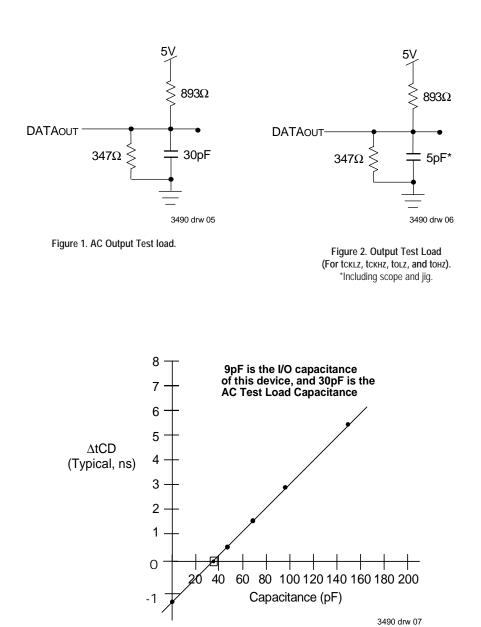


Figure 3. Typical Output Derating (Lumped Capacitive Load).

AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing)⁽³⁾

(Commercial: $V_{CC} = 5V \pm 10\%$, TA = 0°C to +70°C)

			4S12 Only	70914S15 Com'l Only			
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit	
tcyc	Clock Cycle Time	16		20		ns	
tсн	Clock High Time	6	_	6		ns	
tcL	Clock Low Time	6		6	_	ns	
tCD	Clock High to Output Valid		12		15	ns	
ts	Registered Signal Set-up Time	4		4		ns	
tн	Registered Signal Hold Time	1		1		ns	
tDC	Data Output Hold After Clock High	3		3		ns	
t CKLZ	Clock High to Output Low-Z ^(1,2)	2		2		ns	
tскнz	Clock High to Output High-Z ^(1,2)		7		7	ns	
tOE	Output Enable to Output Valid		7		8	ns	
toLz	Output Enable to Output Low-Z ^(1,2)	0		0		ns	
tонz	Output Disable to Output High-Z ^(1,2)		7		7	ns	
tscк	Clock Enable, Disable Set-up Time	4		4		ns	
tнск	Clock Enable, Disable Hold Time	2		2		ns	
ort-to-Port I	Delay						
tcwdd	Write Port Clock High to Read Data Delay		25		30	ns	
tcss	Clock-to-Clock Setup Time		13		15	ns	

70914S20 Com'l Only Min. Max. Unit Parameter Symbol tcyc Clock Cycle Time 20 ns Clock High Time 8 tсн ns 8 tcL Clock Low Time ns tcd Clock High to Output Valid 20 ns Registered Signal Set-up Time 5 ts ____ ns tн Registered Signal Hold Time 1 ns toc Data Output Hold After Clock High 3 ns Clock High to Output Low-Z^(1,2) **t**CKLZ 2 ns Clock High to Output High-Z^(1,2) 9 tскнz ns toe Output Enable to Output Valid 10 ns Output Enable to Output Low-Z^(1,2) 0 tolz ns Output Disable to Output High-Z^(1,2) 9 tонz ns tscĸ Clock Enable, Disable Set-up Time 5 ns 2 Clock Enable, Disable Hold Time tнск ns Port-to-Port Delay Write Port Clock High to Read Data Delay tcwdd 35 ns tcss Clock-to-Clock Setup Time 15 ns

3490 tbl 08b

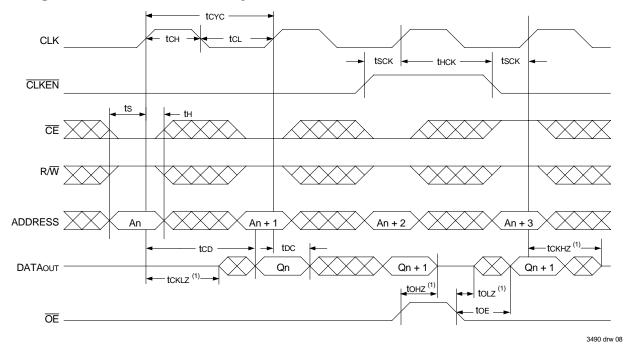
NOTES:

1. Transition is measured 0mV from Low or High impedance voltage with the Output Test Load (Figure 2).

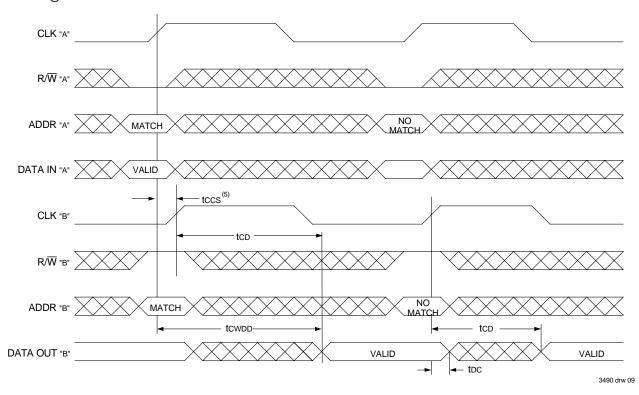
2. This parameter is guaranteed by device characterization, but is not production tested.

3. Industrial temperature: for specific speeds, packages and powers contact your sales office.

Timing Waveform of Read Cycle, Either Side

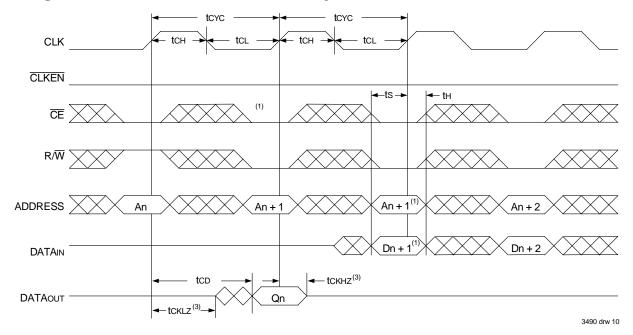


Timing Waveform of Write with Port-to-Port Read^(2,3,4)

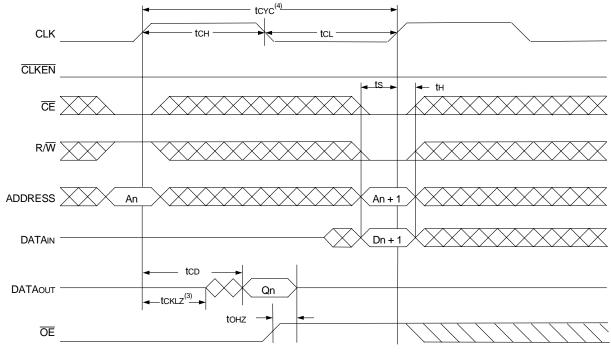


- 1. Transition is measured ±200mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. $\overline{CE}_{L} = \overline{CE}_{R} = VIL, \overline{CLKEN}_{L} = \overline{CLKEN}_{R} = VIL.$
- 3. $\overline{OE} = VIL$ for the reading port, port 'B'.
- 4. All timing is the same for left and right ports. Ports "A" may be either the left or right port. Port "B" is opposite from port "A".
- 5. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwbb.
- If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp. tcwpb does not apply in this case.

Timing Waveform of Read-to-Write Cycle No. $1^{(1,2)}$ (tcyc = min.)



Timing Waveform of Read-to-Write Cycle No. $2^{(4)}$ (tcyc > min.)



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- For tcyc = min.; data out coincident with the rising edge of the subsequent write clock can occur. To ensure writing to the correct address location, the write must be repeated on the second write clock rising edge. If CE = VIL, invalid data will be written into array. The An+1 must be rewritten on the following cycle.
 OE LOW throughout.
- 3. Transition is measured OmV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4. For tcyc > min.; OE may be used to avoid data out coincident with the rising edge of the subsequent write clock. Use of OE will eliminate the need for the write to be repeated.

Functional Description

The IDT70914 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide very short set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal. An asynchronous output enable is provided to ease asynchronous bus interfacing.

The internal write pulse width is dependent on the LOW to HIGH

transitions of the clock signal allowing the shortest possible realized cycle times. Clock enable inputs are provided to stall the operation of the address and data input registers without introducing clock skew for very fast interleaved memory applications.

A HIGH on the \overline{CE} input for one clock cycle will power down the internal circuitry to reduce static power consumption.

Truth Table I: Read/Write Control⁽¹⁾

		Input	S	Outputs	
Sy	nchronou	s ⁽³⁾	Asynchronous		
CLK	ĒĒ	R/W	ŌĒ	I/O0-8	Mode
\uparrow	Н	Х	Х	High-Z	Deselected, Power-Down
\uparrow	L	L	Х	DATAIN	Selected and Write Enabled
\uparrow	L	Н	L	DATAOUT	Read Selected and Data Output Enable Read
\uparrow	Х	Х	Н	High-Z	Outputs Disabled

3490 tbl 09

Truth Table II: Clock Enable Function Table⁽¹⁾

	Inputs		Registe	Register Inputs		Outputs ⁽⁴⁾
Mode	CLK ⁽³⁾	CLKEN ⁽²⁾	ADDR	DATAIN	ADDR	DATAOUT
Load "1"	\uparrow	L	Н	Н	Н	Н
Load "0"	\uparrow	L	L	L	L	L
Hold (do nothing)	↑	Н	Х	Х	NC	NC
х <i>з</i> ,	Х	Н	Х	Х	NC	NC
3490 tbl 10						

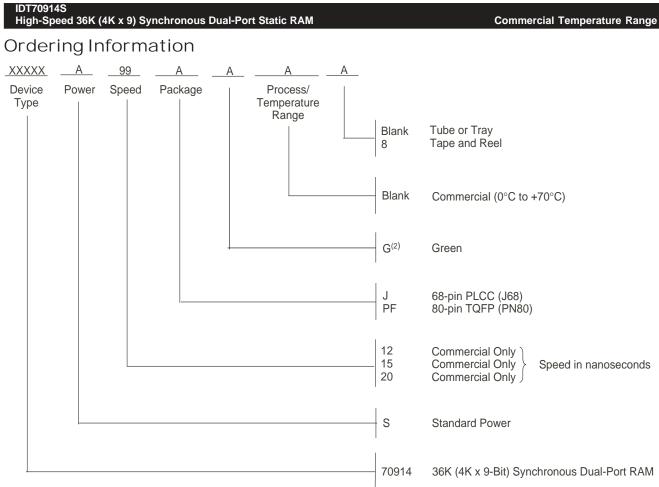
NOTES:

1. 'H' = HIGH voltage level steady state, 'h' = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition, 'L' = LOW voltage level steady state 'l' = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition, 'X' = Don't care, 'NC' = No change

2. CLKEN = VIL must be clocked in during Power-Up.

3. Control signals are initiated and terminated on the rising edge of the CLK, depending on their input level. When R/W and CE are LOW, a write cycle is initiated on the LOW-to-HIGH transition of the CLK. Termination of a write cycle is done on the next LOW-to-HIGH transition of the CLK.

4. The register outputs are internal signals from the register inputs being clocked in or disabled by CLKEN.



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NOTES:

1. Industrial temperature range is available on selected TQFP packages in standard power. For specific speeds, packages and powers contact your sales office.

2. Green parts available. For specific speeds, packages and powers contact your sales office. LEAD FINISH (SnPb) parts are in EOL process. Product Discontinuation Notice - PDN# SP-17-02

Datasheet Document History

3/10/99:	Initiated datasheet document history Converted to new format
	Cosmetic and typographical corrections
	Page 2 and 3 Added additional notes to pin configurations
6/7/99:	Changed drawing format
11/10/99:	Replaced IDT logo
5/24/00:	Page 4 Increased storage temperature parameter
	Clarified TA parameter
	Page 5 DC Electrical parameters-changed wording from "open" to "disabled"
	Changed ±200mV to 0mV in notes
1/12/01:	Removed PGA pinout (obsolete package)
	Changed cycle time of 12ns part from 17ns (58MHz) to 16ns (60MHz)
10/21/08:	Page 11 Removed "IDT" from orderable part number
05/24/10:	Page 1 Added green parts availability to features
	Page 11 Added green indicator to ordering information

Datasheet Document History (con't.)

06/05/15:	Pages 1-12 Removed Military and Industrial Temperature Ranges from datasheet header	
	Page 1	Removed Military speed offerings from the Features
	Page 2	Removed MIL-PRF 38535 QML support information
	Pages 2	3 &11 The package codes J68-1 and PN80-1 changed to J68 and PN80 respectively to match the standard package codes
	Page 4	Removed the military and industrial offerings in the Absolute Max Ratings & the Max Operating Temp tables
	Page 5	Removed the military and industrial offerings in the DC Elec Chars tables
	Page 6	Corrected typo in the Typical Output Derating drawing
	Page 7	Removed military offering for the 20 & 25 speed grades in the AC Elec Chars table
	-	Removed the military temp range information from the AC Elec Chars table title
	Page 11	Added Tape and Reel to and removed military offering & 25ns speed grade from the Ordering Information
04/28/16:	Page 2	Changed diagram for the J68 pin configuration by rotating package pin labels and pin numbers 90 degrees clockwise to reflect pin1 orientation and added pin 1 dot at pin 1
		Removed all four chamfers from J68 and aligned the top and bottom pin labels in the standard direction
	Page 3	Changed diagram for the PN80 pin configuration by rotating package pin labels and pin numbers 90 degrees counter clockwise to reflect pin 1 orientation and added pin 1 dot at pin 1
		Added the IDT logo, changed the text to be in alignment with new diagram marking specs
		for all pin configurations and updated footnote references for the J68 & the PN80 pin configurations
	Page 11	Removed Industrial temp range information from the Ordering Information
02/02/18:	0	Product Discontinuation Notice - PDN# SP-17-02 Last time buy expires June 15, 2018
		Last line buy expires such 13, 2010



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